

Product Change Notification - JAON-13NOYH101

Date: 13 Mar 2018
Product Category: Capacitive Touch Sensors; 8-bit PIC Microcontrollers
Notification subject: CCB 2965.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using CuPdAu bond wire.

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using palladium coated copper wire with gold flash (CuPdAu) bond wire.

Pre Change:

Assembled at ANAC Assembly site with punched as a singulation method, using palladium coated copper wire (PdCu) bond wire and 8290 die attach material.

Post Change:

Assembled at MTAI Assembly site with sawn as a singulation method, using palladium coated copper wire with gold flash (CuPdAu) bond wire and 3280 die attach material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Microchip Technology Thailand – HQ (MTAI)
Wire material	PdCu	CuPdAu
Die attach material	8290	3280
Molding compound material	G700	G700
Lead frame material	C194	C194
Singulation method	Punched	Sawn

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI assembly site with sawn as a singulation method and using palladium coated copper wire with gold flash (CuPdAu) bond wire

Change Implementation Status:
In Progress

Estimated First Ship Date:
April 13, 2018 (date code: 1815)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	March 2018					April 2018				
	09	10	11	12	13	14	15	16	17	
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated Implementation Date							X			

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
March 13, 2018: Issued final notification. This PCN is qualified by similarity (QBS) to PCN # **KSRA-14SZTT575**.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_JAON-13NOYH101_Qual_Report.pdf](#)
 - [PCN_JAON-13NOYH101_Affected_CPN.pdf](#)
 - [PCN_JAON-13NOYH101_Affected_CPN.xlsx](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to **microchipDIRECT** and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

JAON-13NOYH101 - CCB 2965.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_JAON-13NOYH101
CATALOG_PART_NBR
AT42QT1110-MUR
AT42QT11C12-MUR
AT42QT1244-MU
AT42QT2100-MUR
ATMEGA168A-MU
ATMEGA168A-MUR
ATMEGA168PA-MN
ATMEGA168PA-MNR
ATMEGA168PA-MU
ATMEGA168PA-MUR
ATMEGA168PA-MUR431
ATMEGA48-20MU
ATMEGA48-20MUR
ATMEGA48A-MU
ATMEGA48A-MUR
ATMEGA48P-20MU
ATMEGA48P-20MUR
ATMEGA48PA-MN
ATMEGA48PA-MNR
ATMEGA48PA-MU
ATMEGA48PA-MUR
ATMEGA48PV-10MU
ATMEGA48PV-10MUR
ATMEGA48V-10MU
ATMEGA48V-10MUR
ATMEGA48V-10MUR173
ATMEGA48V-10MUR348
ATMEGA8-16MU
ATMEGA8-16MUR
ATMEGA88-20MU
ATMEGA88-20MUR
ATMEGA88-20MURA4
ATMEGA88A-MU
ATMEGA88A-MUR
ATMEGA88P-20MU
ATMEGA88P-20MUR
ATMEGA88PA-MN
ATMEGA88PA-MNR
ATMEGA88PA-MU
ATMEGA88PA-MUR
ATMEGA88PA-MURA06
ATMEGA88PA-MURA6
ATMEGA88PV-10MU

JAON-13NOYH101 - CCB 2965.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_JAON-13NOYH101
CATALOG_PART_NBR
ATMEGA88PV-10MUR
ATMEGA88V-10MU
ATMEGA88V-10MUR
ATMEGA88V-10MUR360
ATMEGA88V-10MUR378
ATMEGA88V-10MUR379
ATMEGA8A-MN
ATMEGA8A-MNR
ATMEGA8A-MU
ATMEGA8A-MUR
ATMEGA8A-MURA7
ATMEGA8L-8MU
ATMEGA8L-8MUA4
ATMEGA8L-8MUR
ATMEGA8L-8MURA3
ATTINY26-16MU
ATTINY26-16MUR
ATTINY261A-MFRA0
ATTINY261A-MN
ATTINY261A-MNR
ATTINY261A-MU
ATTINY261A-MUR
ATTINY26L-8MU
ATTINY26L-8MUR
ATTINY28L-4MU
ATTINY28L-4MUR
ATTINY28V-1MU
ATTINY28V-1MUR
ATTINY461-20MU
ATTINY461-20MUR
ATTINY461-20MUR553
ATTINY461A-MU
ATTINY461A-MUR
ATTINY461V-10MU
ATTINY461V-10MUR
ATTINY48-MU
ATTINY48-MUR
ATTINY48-MUR522
ATTINY48-MUR547
ATTINY861-20MU
ATTINY861-20MUR
ATTINY861-20MUR430
ATTINY861A-MU

JAON-13NOYH101 - CCB 2965.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using CuPdAu bond wire.

Affected Catalog Part Numbers (CPN)

PCN_JAON-13NOYH101
CATALOG_PART_NBR
ATTINY861A-MUR
ATTINY861V-10MU
ATTINY861V-10MUR
ATTINY88-MU
ATTINY88-MUR